

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 09-293904

(43)Date of publication of application : 11.11.1997

(51)Int.Cl.

H01L 33/00

(21)Application number : 08-107293

(71)Applicant : NICHIA CHEM IND LTD

(22)Date of filing : 26.04.1996

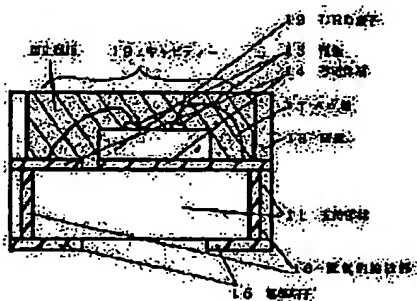
(72)Inventor : IZUNO KUNIHIRO
TAKEUCHI ISATO
KANBARA YASUO

(54) LED PACKAGE

(57)Abstract

PROBLEM TO BE SOLVED: To enable an LED device to deteriorate less in emission output and to be increased in mounting reliability when it is mounted on a feeder circuit board, by soldering by a method wherein the light emission peak of the LED device is set lower in wavelength than a specific value, the surface of a dielectric layer is covered with a silver-white precious metal, and the surface of an electrode terminal is coated with Au.

SOLUTION: A conductor layer 14 which feeds an electric power to the electrode 13 of an LED device 12 is formed on the surface of a support member 11, and an electrode terminal 15 where an electric power is fed from an external feeder circuit board is provided to the rear of the support member 11 and connected to the conductor layer 14 with an electrical connector 16. The surface of the conductor layer 14 is coated with silver-white precious metal, and the surface of the electrode terminal 15 is covered with Au. The emission light peak of the LED device 12 is set shorter than 600nm in wavelength. By this setup, light emitted from an LED device of emission peak wavelength 600nm can be reflected, and the LED device which is soldered high in strength to a feeder circuit board and high in efficiency and output power can be obtained.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]